

**FM120-MH THRU FM1100-MH**

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# FM120-MH THRU FM1100-MH

## 1.0A Surface Mount Schottky Barrier Rectifiers - 20V-100V

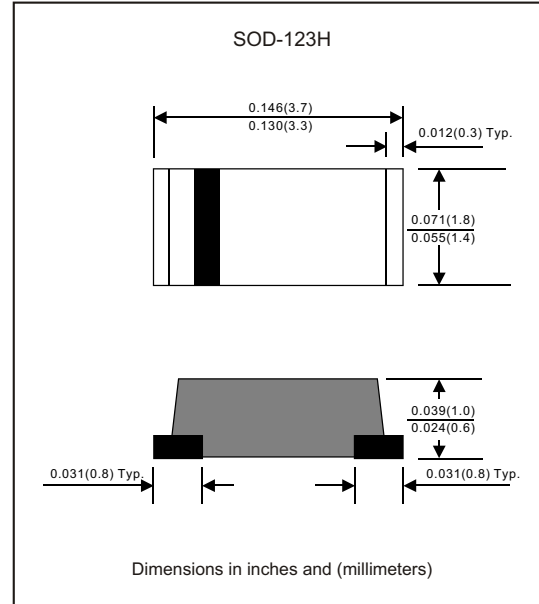
### Features

- Batch process design, excellent power dissipation offers better reverse leakage current and thermal resistance.
- Low profile surface mounted application in order to optimize board space.
- Tiny plastic SMD package.
- Low power loss, high efficiency.
- High current capability, low forward voltage drop.
- High surge capability.
- Guardring for overvoltage protection.
- Ultra high-speed switching.
- Silicon epitaxial planar chip, metal silicon junction.
- Lead-free parts meet environmental standards of MIL-STD-19500 /228

### Mechanical data

- Epoxy : UL94-V0 rated flame retardant
- Case : Molded plastic, SOD-123H
- Terminals :Plated terminals, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Mounting Position : Any
- Weight : Approximated 0.011 gram

### Package outline



### Maximum ratings (AT T<sub>A</sub>=25°C unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	See Fig.1	I <sub>O</sub>			1.0	A
Forward surge current	8.3ms single half-sine-wave superimposed on rate load (JEDEC method)	I <sub>FSM</sub>			25	A
Reverse current	V <sub>R</sub> = V <sub>RRM</sub> T <sub>A</sub> = 25°C	I <sub>R</sub>			0.5	mA
	V <sub>R</sub> = V <sub>RRM</sub> T <sub>A</sub> = 125°C				10	
Thermal resistance	Junction to ambient	R <sub>θJA</sub>		98		°C/W
Diode junction capacitance	f=1MHz and applied 4V DC reverse voltage	C <sub>J</sub>		120		pF
Storage temperature		T <sub>STG</sub>	-65		+175	°C

SYMBOLS	V <sub>RRM</sub> <sup>*1</sup> (V)	V <sub>RMS</sub> <sup>*2</sup> (V)	V <sub>R</sub> <sup>*3</sup> (V)	V <sub>F</sub> <sup>*4</sup> (V)	Operating temperature T <sub>J</sub> , (°C)
FM120-MH	20	14	20	0.50	-55 to +125
FM130-MH	30	21	30		
FM140-MH	40	28	40		
FM150-MH	50	35	50	0.70	-55 to +150
FM160-MH	60	42	60		
FM180-MH	80	56	80		
FM1100-MH	100	70	100	0.85	

\*1 Repetitive peak reverse voltage

\*2 RMS voltage

\*3 Continuous reverse voltage

\*4 Maximum forward voltage

## Rating and characteristic curves (FM120-MH THRU FM1100-MH)

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

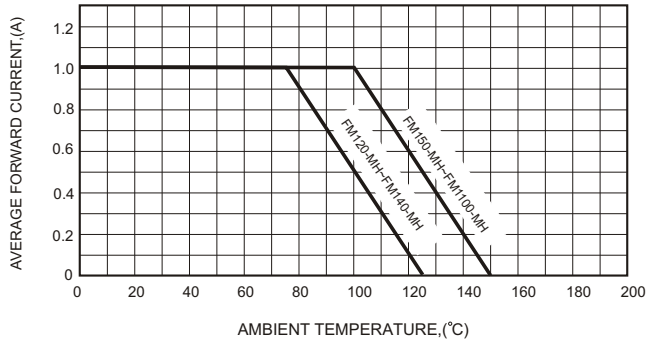


FIG.2-TYPICAL FORWARD CHARACTERISTICS

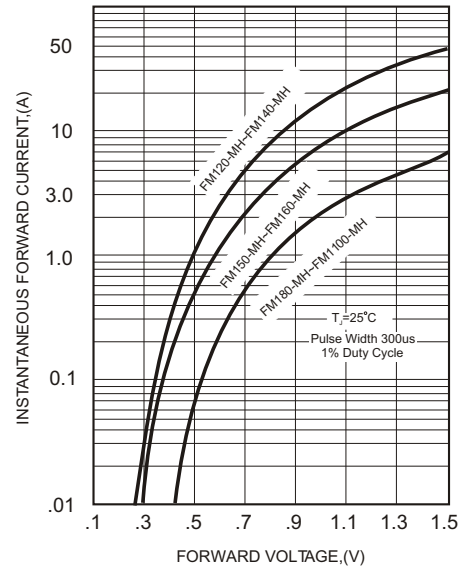


FIG.3-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

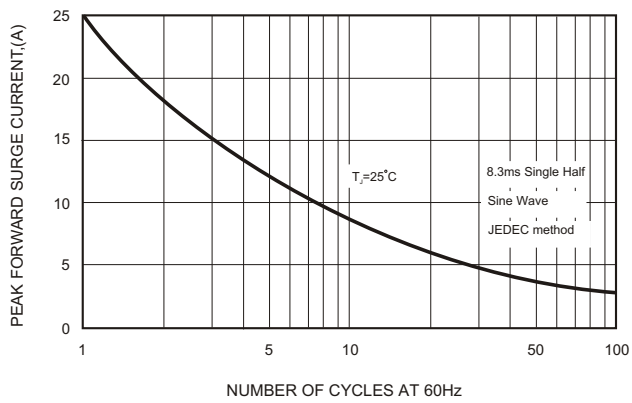


FIG.5 - TYPICAL REVERSE CHARACTERISTICS

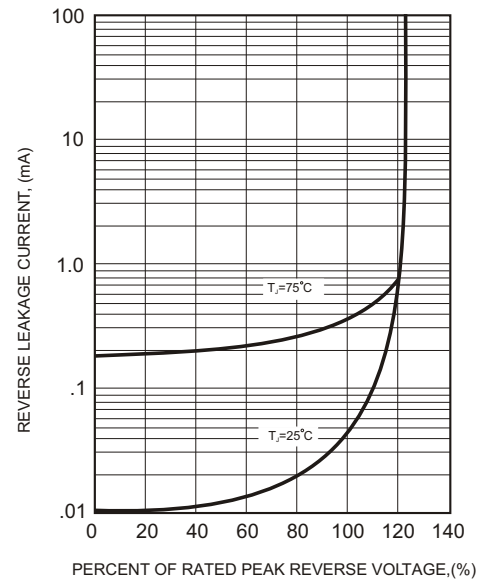
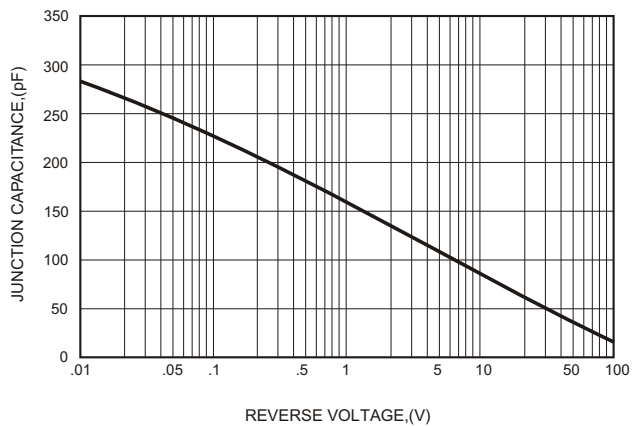




FIG.4-TYPICAL JUNCTION CAPACITANCE



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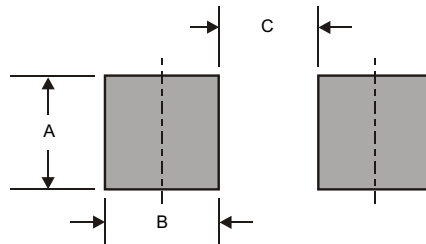
## Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

## Marking

Type number	Marking code
FM120-MH	12
FM130-MH	13
FM140-MH	14
FM150-MH	15
FM160-MH	16
FM180-MH	18
FM1100-MH	10

## Suggested solder pad layout

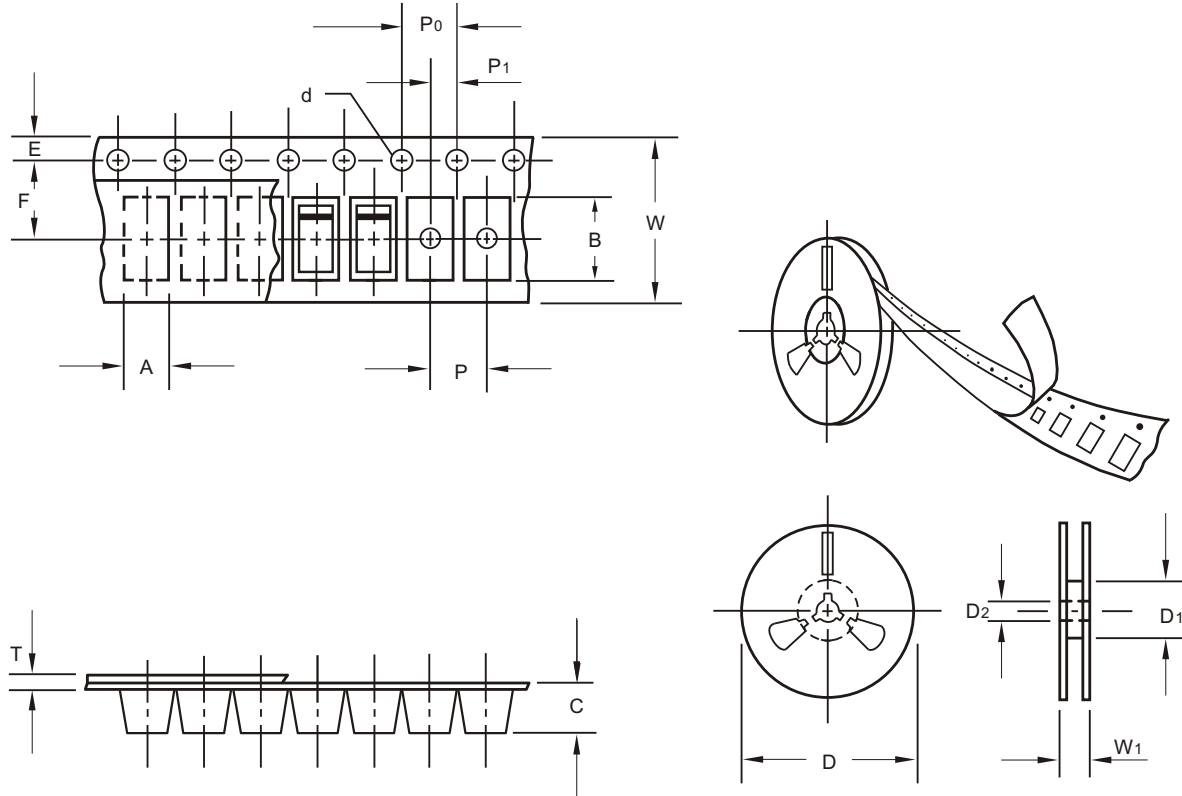


Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SOD-123H	0.071 (1.80)	0.051 (1.30)	0.067 (1.70)

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Packing information



unit:mm

Item	Symbol	Tolerance	SOD-123H
Carrier width	A	0.1	2.00
Carrier length	B	0.1	3.85
Carrier depth	C	0.1	1.10
Sprocket hole	d	0.1	1.50
13" Reel outside diameter	D	2.0	-
13" Reel inner diameter	D1	min	-
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D1	min	62.00
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	3.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.23
Tape width	W	0.3	8.00
Reel width	W1	1.0	11.40

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

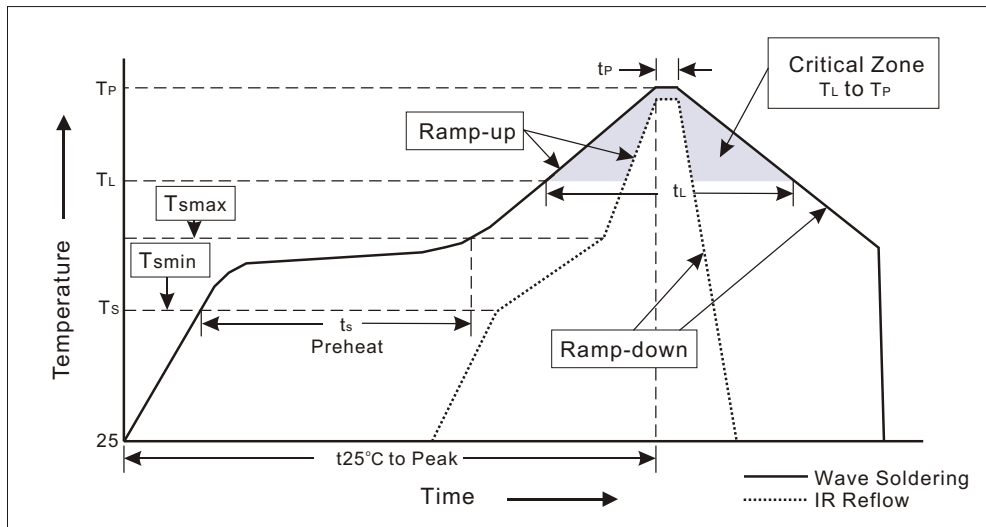
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## Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA. (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SOD-123H	7"	3000	4.0	12,000	185*185*51	178	360*360*220	120,000	5.8

## Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=10°C~35°C Humidity=65%±15%
- 2.Reflow soldering of surface-mount devices



### 3.Flow (wave)soldering (solder dipping)

Profile Feature	Soldering Condition
Average ramp-up rate(TL to TP)	<3°C/sec
Preheat -Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(min to max)(ts)	100°C 150°C 60~120sec
Tsmax to TL -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(TL) -Time(tL)	183°C 60~150sec
Peak Temperature(TP)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(tp)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes

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## High reliability test capabilities

Item Test	Conditions	Reference
1. Solder Resistance	at 260±5°C for 10±2sec. immerse body into solder 1/16"±1/32"	MIL-STD-750D METHOD-2031
2. Solderability	at 245±5°C for 5 sec.	MIL-STD-202F METHOD-208
3. High Temperature Reverse Bias	V <sub>R</sub> =80% rate at T <sub>A</sub> =125°C for 168 hrs.	MIL-STD-750D METHOD-1026
4. Forward Operation Life	Rated average rectifier current at T=25°C for 500hrs.	MIL-STD-750D METHOD-1027
5. Intermittent Operation Life	T <sub>A</sub> = 25°C, I <sub>F</sub> = I <sub>O</sub> On state: power on for 5 min. off state: power off for 5 min. on and off for 500 cycles.	MIL-STD-750D METHOD-1036
6. Pressure Cooker	15P <sub>sig</sub> at T <sub>A</sub> =121°C for 4 hrs.	
7. Temperature Cycling	-55°C to +125°C dwelled for 30 min. and transferred for 5 min. total 10 cycles.	MIL-STD-750D METHOD-1051
8. Thermal Shock	0°C for 5 min. rise to 100°C for 5 min. total 10 cycles.	MIL-STD-750D METHOD-1056
9. Forward Surge	8.3ms single half sine-wave superimposed on rated load, one surge.	MIL-STD-750D METHOD-4066-2
10. Humidity	at T <sub>A</sub> =65°C, RH=98% for 1000hrs.	MIL-STD-750D METHOD-1038
11. High Temperature Storage Life	at 175°C for 1000 hrs.	MIL-STD-750D METHOD-1031
12. Solvent Resistance	Dip into Freon at 25°C for 1 min.	MIL-STD-202F METHOD-215